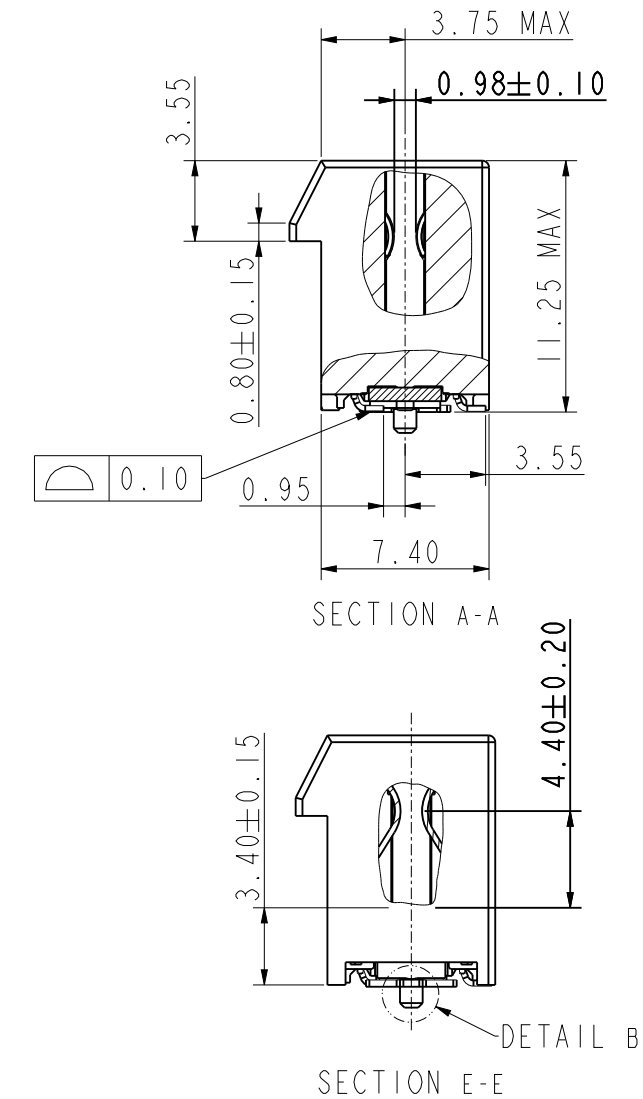
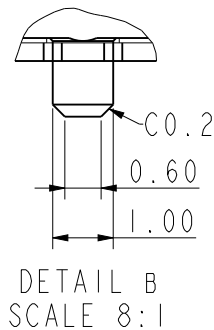
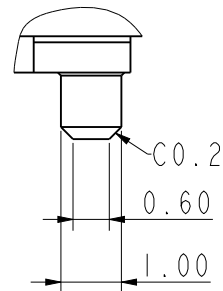
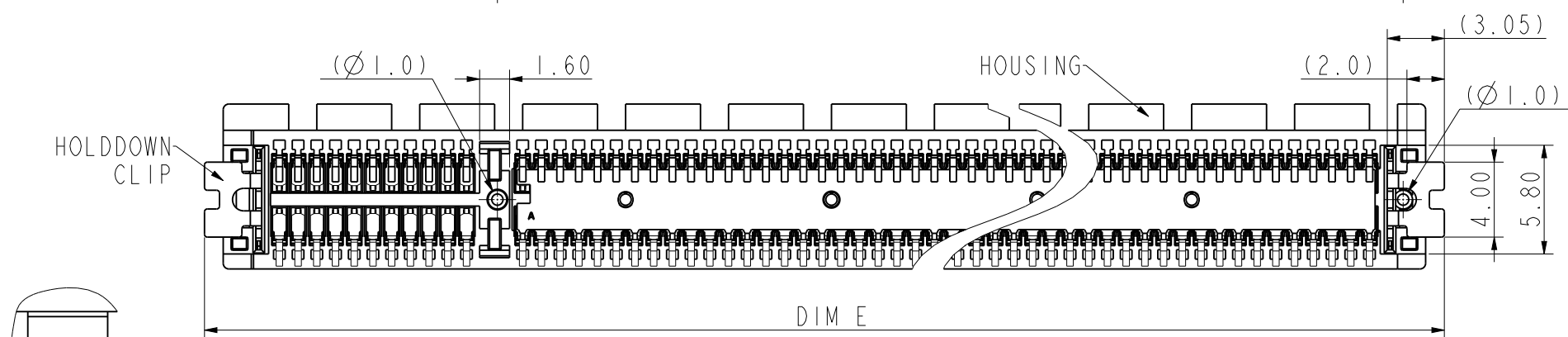
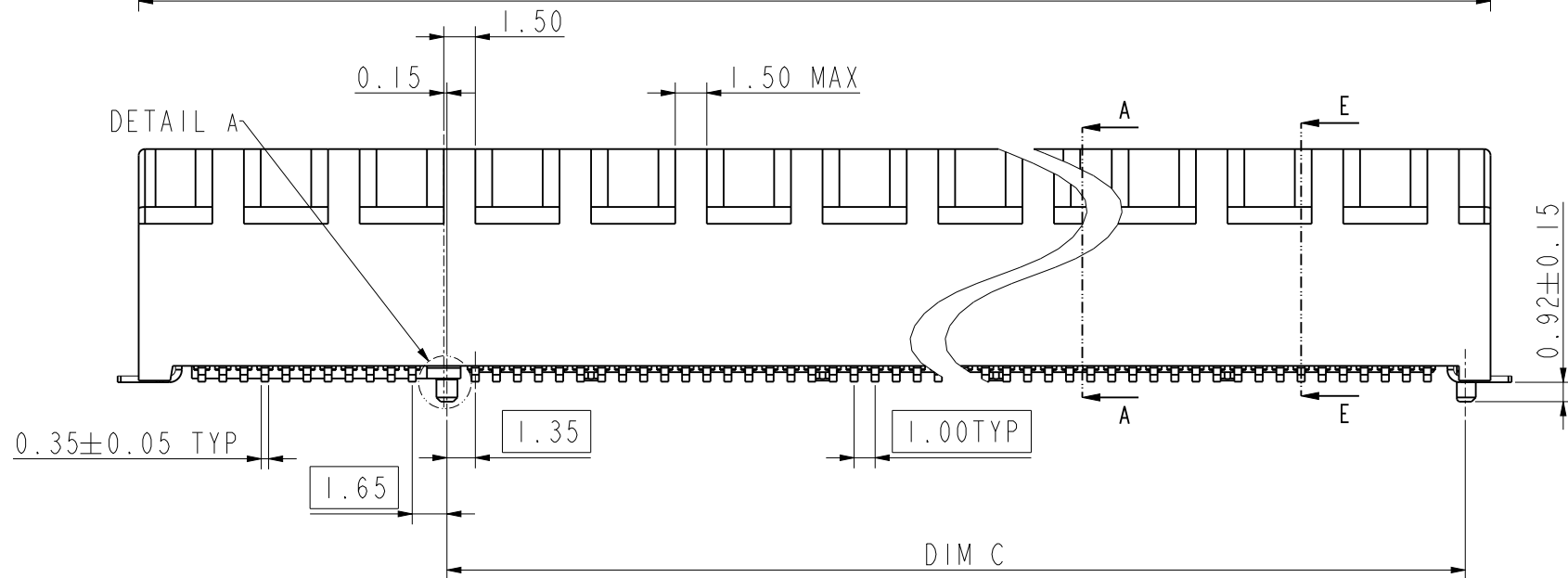
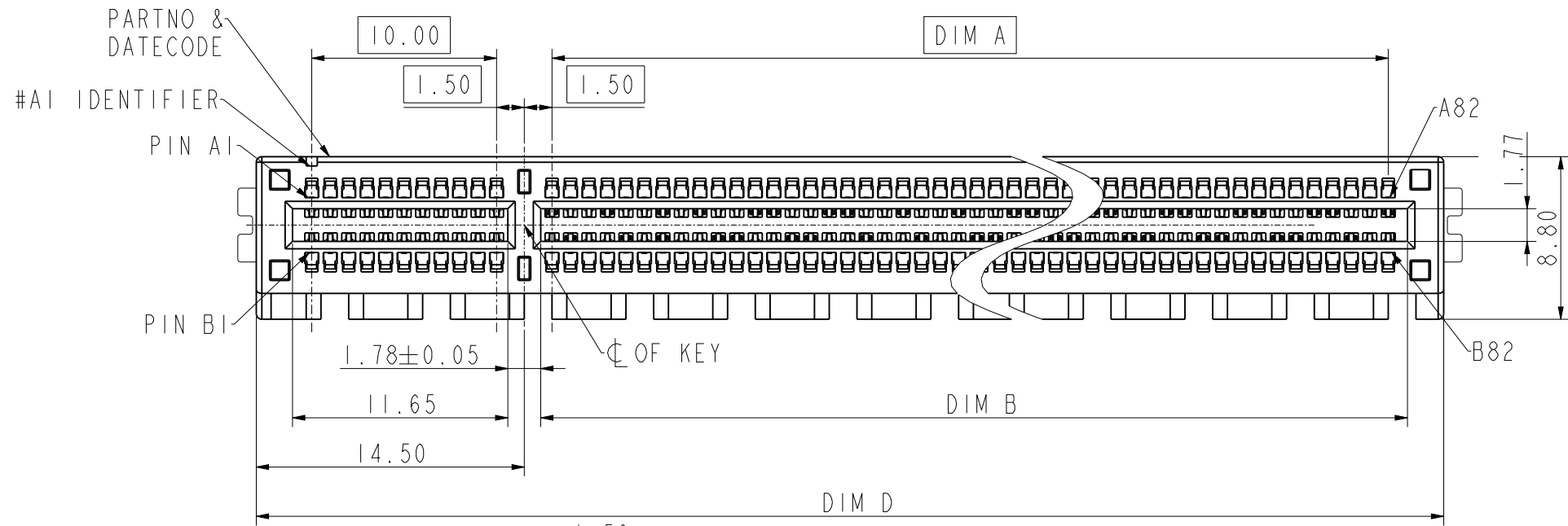
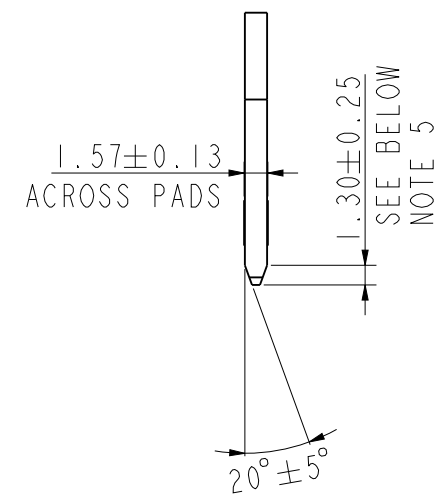
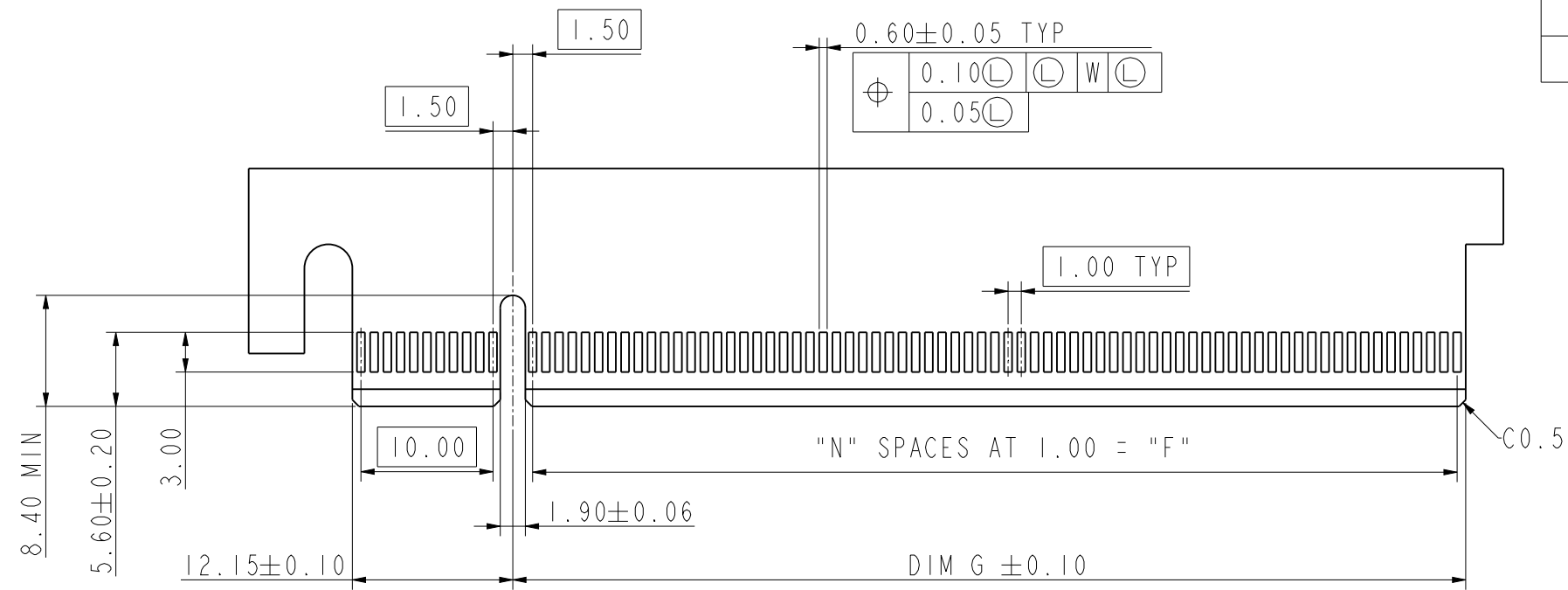




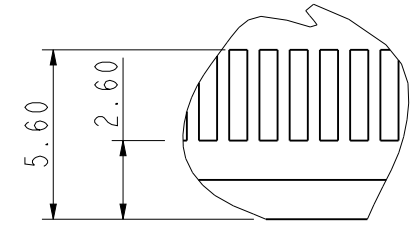
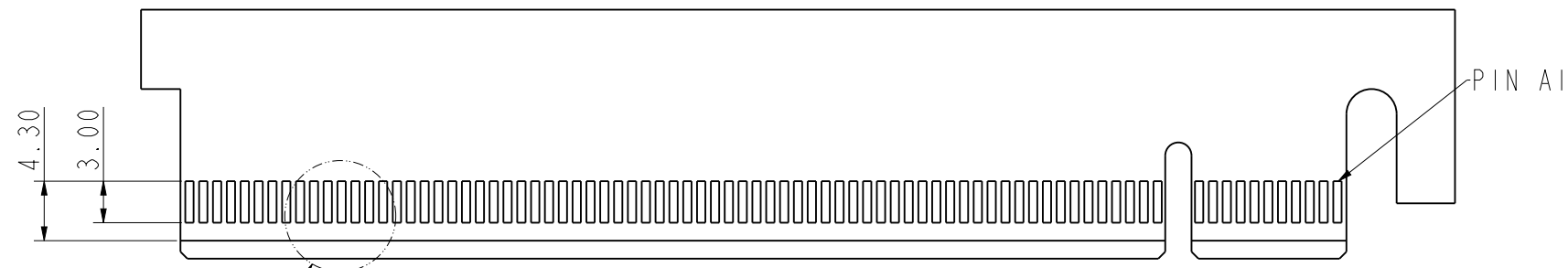
revision history				
rev	ecn no	description	dr	date
XI	CD----	THE FRIST DRAWING	MO	2022/10/15
-	-	-	-	-
-	-	-	-	-

spec ref				dr		Mark.qiu		Oct.15,2022		Amphenol				mm		scale		size					
tolerance std		TOLERANCES UNLESS OTHERWISE SPECIFIED		eng		Mark.qiu		Oct.15,2022						ecn no				1:1		A3			
				rvwr																			
				appr										amphenol-icc.com				rel level		PROPOSAL			
surface		linear		0.X		±0.30		projection		title		PCI Express Gen5 (32Gb/s)				drawing no		C CEM01641001460X				rev	
				0.XX		±0.20																	
				0.XXX		±0.10																	
				angular		0°		±2°						SMT,LL FLIP TERMINAL TYPE				cat. no.				XI	
						product family						PCIe						sheet 1 of 5					

CONNECTOR LINK WIDTH	POSITION	N	DIM G	DIM F
X1	36	6	8.15	6.00
X4	64	20	22.15	20.00
X8	98	37	39.15	37.00
X16	164	70	72.15	70.00



← I/O PANEL DIRECTION
PRIMARY (COMPONENT) SIDE

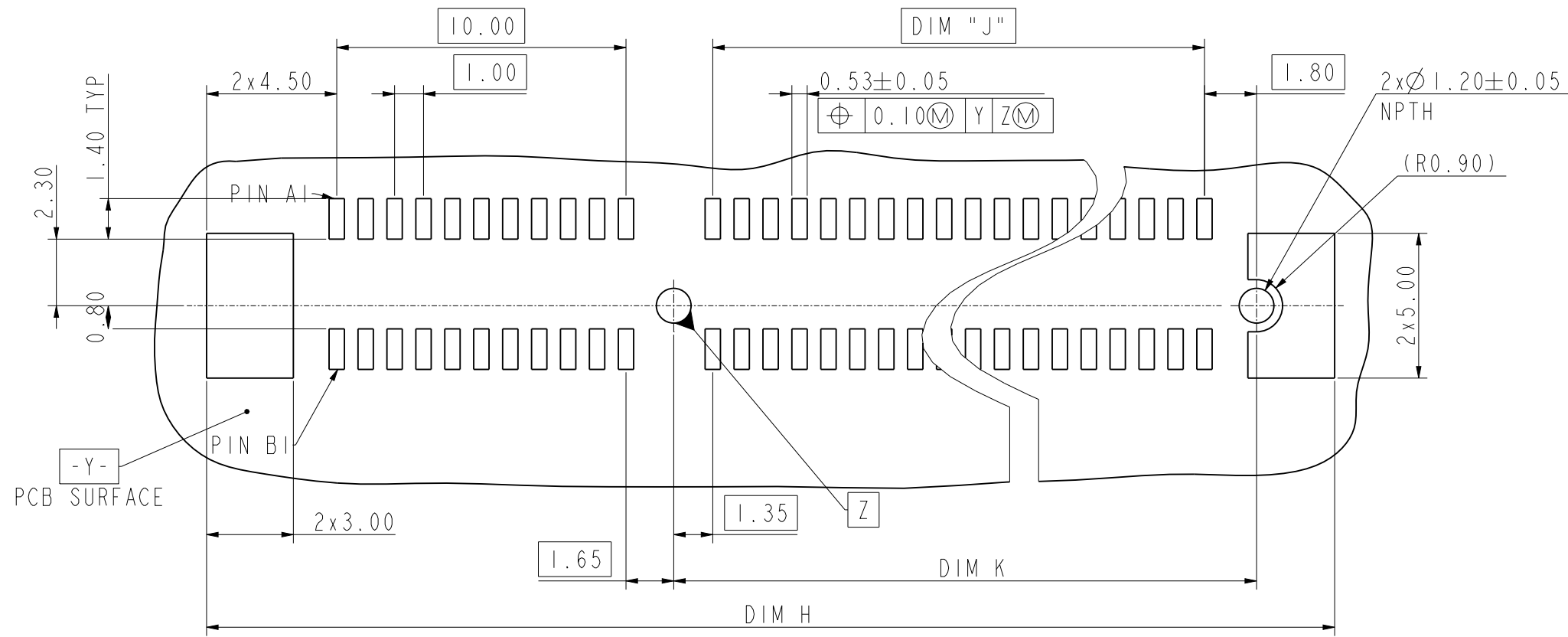


DETAIL C
SCALE 4:1

I/O PANEL DIRECTION →
SECONDARY (SOLDER) SIDE

1. NO TIE BAR PERMITTED FROM CARD EDGE TO LEADING EDGE OF PAD FOR PIN A1 AND PIN "L".
2. CHAMFER EDGES MUST BE FREE FROM CUTTING BURRS.
3. TOLERANCES : ± 0.13 .
4. CONTACT AFCI ENGINEERING FOR SI REPORT.
5. ADD-IN-CARD GOLD FINGER DESIGN REFERENCED CEM REV 5.0 VER 0.7 JUNE 29, 2020.

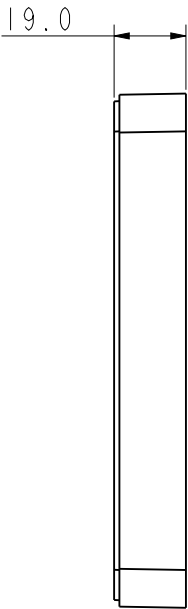
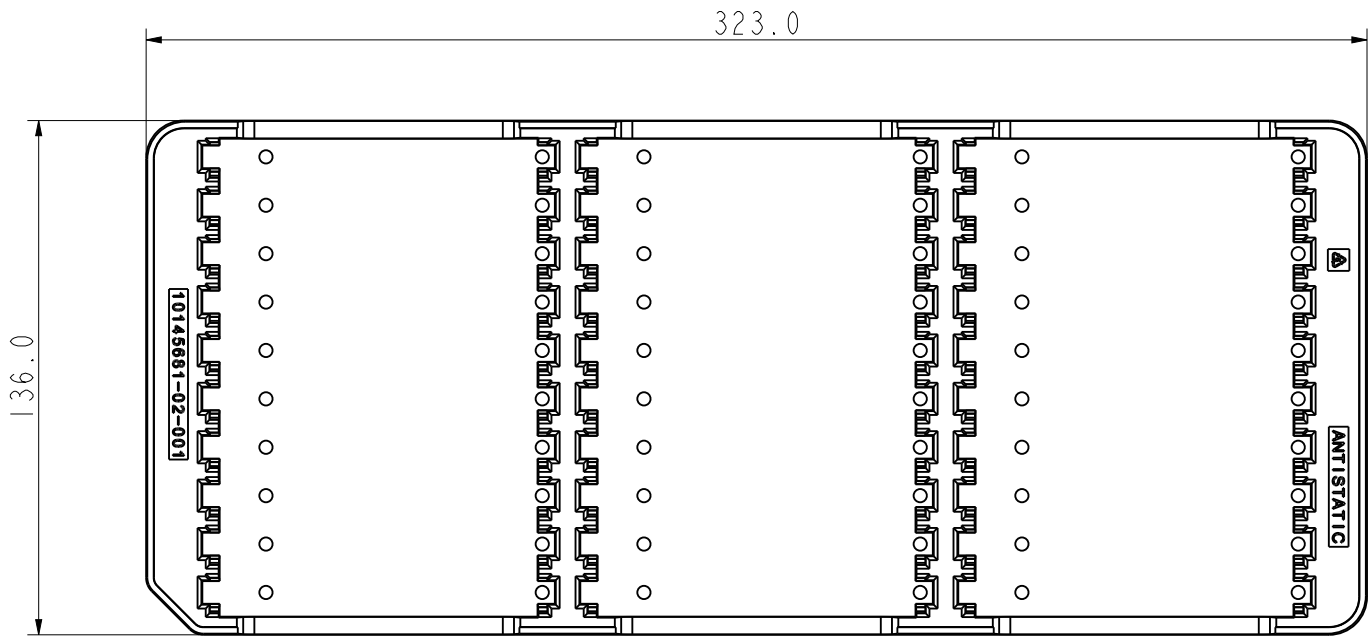
spec ref		dr	Mark.qiu	Oct.15,2022	Amphenol	mm	scale	size
tolerance std		eng	Mark.qiu	Oct.15,2022		ecn no	1:1	A3
TOLERANCES UNLESS OTHERWISE SPECIFIED		rvwr				rel level		
		appr				PROPOSAL		
surface	✓	linear	0.X	±0.30	projection	PCI Express Gen5 (32Gb/s)	cat. no.	rev
			0.XX	±0.20				
			0.XXX	±0.10				
		angular	0°	±2°		SMT,LL FLIP TERMINAL TYPE		X1
product family						PCIe		sheet 2 of 5



RECOMMENDED PCB LAYOUT, PAD TYPE

DIMENSIONS									
POSITION	A	B ^{+0.15} _{-0.05}	C ±0.10	D ±0.23	E ±0.20	H ±0.10	J	K ±0.10	L
36	6.00	7.65	9.15	25.00	27.00	28.00	6.00	9.15	6.70
64	20.00	21.65	23.15	39.00	41.00	42.00	20.00	23.15	20.70
98	37.00	38.65	40.15	56.00	58.00	59.00	37.00	40.15	37.70
164	70.00	71.65	73.15	89.00	91.00	92.00	70.00	73.15	70.70

spec ref				dr		Mark.qiu		Oct.15,2022		Amphenol				mm		scale		size							
tolerance std		TOLERANCES UNLESS OTHERWISE SPECIFIED				eng		Mark.qiu						Oct.15,2022		←→				1:1		A3			
						rvwr																			
						appr																			
										amphenol-icc.com				ecn no		PROPOSAL									
														rel level											
surface		✓		linear		0.X		±0.30		projection		title		PCI Express Gen5 (32Gb/s)				diag no		C CEM01641001460X				rev	
						0.XX		±0.20																	
						0.XXX		±0.10																	
						angular		0°																	



NOTE:
1: TRAY MATERIAL: HIPS BLACK
2: PACKING QTR:30PCS/TRAY
300PCS/CARTON

spec ref				dr		Mark.qiu		Oct.15,2022		Amphenol				mm		scale		size							
tolerance std				eng		Mark.qiu		Oct.15,2022						←→				1:1				A3			
				rvwr																					
				appr																					
TOLERANCES UNLESS OTHERWISE SPECIFIED										amphenol-icc.com				ecn no		PROPOSAL									
														rel level											
surface ✓				linear		0.X		±1.00		projection		title		PCI Express Gen5 (32Gb/s)				dwg no		C CEM01641001460X				rev	
						0.XX		±0.50																	
						0.XXX		±0.20																	
				angular		0°		±2°		SMT,LL FLIP TERMINAL TYPE				cat. no.				XI							
								product family				PCIe				sheet 4 of 5									

PRODUCT NUMBER CODE

NOTES:

- 1. MATERIAL:
HOUSING: HIGH PERFORMANCE RESIN, GLASS FILLED, UL 94V-0
CONTACT: COPPER ALLOY.
HOLDDOWN CLIP: COPPER ALLOY
- 2. PLATING:
CONTACT: UNDERPLATE: 50u" NICKEL OVER ALL.
SOLDER AREA: 100u" TIN (LEAD FREE).
MATING AREA: SEE PRODUCT NUMBER CODE.
HOLDDOWN CLIP: 100u" TIN OVER 50 u" NICKEL.
- 3. PRODUCT SPECIFICATION: GS-12-1406
- 4. PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND
OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-47-004.
- 5. DATE CODE "MMDDYYX", MMDDYY IS ASSEMBLY DATE.
- 6. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°
PEAK TEMPERATURE FOR 10 SECONDS IN A
CONVECTION, INFRA-RED OR VAPOR PHASE
REFLOW OVEN.
- 7. THERE IS GROUND BUSSING WITHIN THE CONNECTOR SYSTEM.
FOR DIFFERENTIAL PAIR'S GROUND LOCATION, PLEASE REFER TO THE
CONNECTOR PINOUT TABLE FROM
CHAPTER 6 OF PCI EXPRESS CARD
ELECTROMECHANICAL SPECIFICATION.

CEM01641001460X

NO. OF POSITION
164: 164 POSITIONS

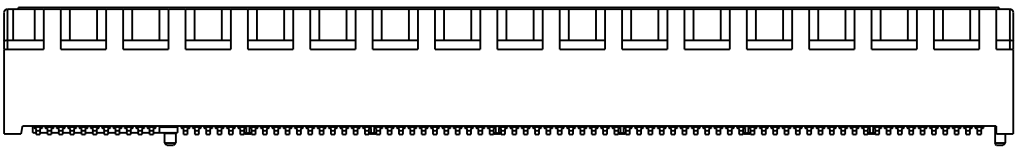
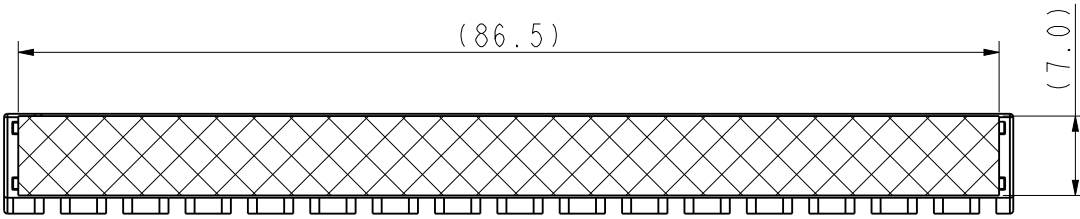
CAP&KAPTON TAPE
1: KAPTON TAPE

PACKAGING OPTIONS
4: HARD TRAY(323*136mm)

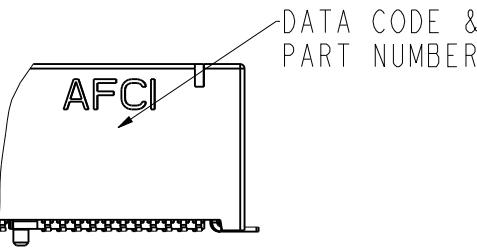
PLATING SPEC
1 0.76um Au
2 0.38um Au
3 GOLD FLASH

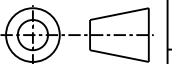
TRANSMISSION SPEED
0 PCIe Gen5/32Gbps

SOLDER TAIL OPTION
6 LL FLIP TAIL



POSITION OF KAPTON TAPE



spec ref				dr		Mark.qiu		Oct.15,2022		Amphenol				mm		scale		size					
tolerance std		TOLERANCES UNLESS OTHERWISE SPECIFIED		eng		Mark.qiu		Oct.15,2022						amphenol-icc.com				ecn no					
				rvwr														rel level PROPOSAL					
				appr																			
surface		✓	linear	0.X		±0.30		projection 		title	PCI Express Gen5 (32Gb/s)				deg no	C CEM01641001460X				rev			
				0.XX		±0.20																	
				0.XXX		±0.10																	
				angular		0°																±2°	
												product family				PCIe				sheet 5 of 5			
												cat. no.				X1							